

Opto-isolateurs de sortie RCS et Triac (suite)



Fig.	Tension d'isolement	Déclencheur Max I _F (mA)	Tension de blocage minimale	IORM max.	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
31	3750	60	250	100nA	MFP	FODM3011R1_NF098CT-ND‡	.74	.58	.42
	3750	60	250	100nA	MFP	FODM3011R1_NF098TR-ND◊	156.42/500		
	3750	60	250	100nA	MFP	FODM3012R1_NF098CT-ND‡	.84	.66	.47
	3750	60	250	100nA	MFP	FODM3012R1_NF098TR-ND◊	177.28/500		
	3750	60	600	100nA	MFP	FODM3052R1_NF098CT-ND‡	1.10	.90	.62
	3750	60	600	100nA	MFP	FODM3052R1_NF098TR-ND◊	233.26/500		
32	3750	60	600	100nA	MFP	FODM3053R1_NF098CT-ND‡	1.19	.97	.67
	3750	60	600	100nA	MFP	FODM3053R1_NF098TR-ND◊	251.92/500		
	3750	60	600	500nA	MFP	FODM3062-ND	1.53	1.25	.87
	3750	60	600	500nA	MFP	FODM3063-ND	1.69	1.37	.95
	3750	60	800	500nA	MFP	FODM3082-ND	1.92	1.71	1.10
	3750	60	800	500nA	MFP	FODM3083-ND	1.98	1.76	1.14
36	7500	60	5300	100nA	SMD	MOC3021SR2MCT-ND	.78	.60	.43
	7500	60	5300	100nA	SMD	MOC3021SR2MTR-ND	233.26/1,000		
	7500	60	5300	100nA	SMD	MOC3023SR2MCT-ND	.78	.61	.44
	7500	60	5300	100nA	SMD	MOC3023SR2MTR-ND	234.64/1,000		
	7500	60	5300	100nA	SMD	MOC3052SM-ND	.88	.72	.50
	7500	60	5300	100nA	SMD	MOC3052SR2MCT-ND	1.05	.81	.58
37	7500	60	5300	100nA	SMD	MOC3052SR2MTR-ND	315.59/1,000		
	7500	60	5300	100nA	DIP	MOC3052TVM-ND	.88	.72	.50
	7500	60	5300	100nA	SMD	MOC3043SM-ND	1.02	.84	.58
	7500	60	5300	500nA	DIP	MOC3063TVM-ND	1.17	.96	.66
	7500	60	5300	500nA	SMD	MOC3083SR2MCT-ND	1.48	1.19	.83
	7500	60	5300	500nA	SMD	MOC3083SR2MTR-ND	461.04/1,000		

† Approbation VDE ▲ Écartement entre les broches : 0.4" ‡ Bande coupée ◊ Bande et bobine

Pièces d'accouplement à 4 broches



Fig.	Tension	Rapport de transfert de courant	V _{CEO} (max.)	tpassant/bloqué typ. (µsec.)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
14A	2500	50-600%	80	3/3	MFP	HMHAA281-ND†	.42	.34	.26
	5000	40-80%	70	4/3	DIP	FOD617A-ND†	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617D-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617E-ND†	.43	.32	.21
14B	5000	40-80%	70	4/3	DIP	FOD617A300-ND†	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B300-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C300-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617D300-ND†	.43	.32	.21
	5000	20-300%	70	4/3	DIP	FOD814-ND	.48	.38	.28
	5000	20-300%	70	4/3	SMD	FOD814S-ND	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD814SDCT-ND‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD814SDTR-ND◊	329.31/2,000		
	5000	20-300%	70	4/3	DIP	FOD814W-ND▲	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300-ND†	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300W-ND†▲	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143S-ND†	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143SDCT-ND‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD8143SDTR-ND◊	329.31/2,000		
	5000	50-150%	70	4/3	DIP	FOD814A-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814AS-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814ASDCT-ND‡	.55	.43	.31
	5000	50-150%	70	4/3	SMD	FOD814ASDTR-ND◊	182.22/1,000		
5000	50-150%	70	4/3	DIP	FOD814AW-ND▲	.47	.38	.27	
5000	50-150%	70	4/3	DIP	FOD814A300-ND†	.44	.35	.25	
5000	50-150%	70	4/3	DIP	FOD814A300W-ND†▲	.48	.38	.28	
5000	50-150%	70	4/3	SMD	FOD814A3S-ND†	.44	.35	.25	
5000	50-150%	70	4/3	SMD	FOD814A3SDCT-ND‡	.55	.43	.31	
5000	50-150%	70	4/3	SMD	FOD814A3SDTR-ND◊	182.22/1,000			
14C	2500	50-600%	7	3/3	DIP	HMHAA280R1CT-ND‡	.43	.33	.25
	2500	50-600%	7	3/3	DIP	HMHAA280R1TR-ND◊	75.89/500		
	2500	50-600%	80	3/3	MFP	HMHAA280R4VCT-ND‡	.43	.33	.25
	2500	50-600%	80	3/3	MFP	HMHAA280R4VTR-ND◊	352.35/2,500		
14D	5000	600-7500%	35	60/53	SMD	FOD816S-ND	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD816SDCT-ND‡	.60	.47	.34
	5000	600-7500%	35	60/53	SMD	FOD816SDTR-ND◊	198.93/1,000		
	5000	600-7500%	35	60/53	DIP	FOD816W-ND▲	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300-ND†	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300W-ND†▲	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD8163S-ND†	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD8163SDCT-ND‡	.60	.47	.34
	5000	600-7500%	35	60/53	SMD	FOD8163SDTR-ND◊	198.93/1,000		
	5000	600-7500%	35	60/53	SMD	FOD8163SDTR-ND◊	198.93/1,000		

† Approbation VDE ▲ Écartement entre les broches : 0.4" ‡ Bande coupée ◊ Bande et bobine

Fig.	Fonction	Entrée : sortie LSTTL	Configuration de sortie du débit en bauds : 15 Mo	Type de boîtier	N° de référence Digi-Key	Prix unitaire			Bande et bobine◊	
						1	10	100	Qté	Prix
26	Séparateur	TTL	Totem pôle	SMD	HCPL2630S-ND	3.13	2.80	1.82	—	—
33	Séparateur	TTL	Totem pôle	SMD	FOD0708R1CT-ND‡	3.52	2.94	2.14	500	773.73
34	Séparateur	TTL	Totem pôle	SMD	FOD0710-ND	3.37	2.70	2.10	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0720-ND	2.33	1.86	1.45	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0721-ND	2.56	2.05	1.59	—	—
35	Séparateur	TTL	Totem pôle	SMD	FOD0738R1CT-ND‡	6.88	5.73	4.17	1,000	2771.21

Fig.	Tension d'isolement	Courant I _{on} (max.) mA	ICCL (max.)	Tension de fonc. (max.) mV	Type boîtier	N° de référence Digi-Key	Prix unitaire			Prix de bande et bobine◊
							1	10	100	
36	5000	1.6	7.0	2.0	SMD	FOD2200SDVCT-ND‡	2.71	2.43	1.57	981.08
37	2500	50	13	5.5	SOIC	HCPL0600-ND	2.44	2.19	1.42	—
	3750	50	13	5.5	SOIC	HCPL0601-ND	3.00	2.69	1.74	—
	2500	50	13	7.0	SMD	6N137SDCT-ND‡	1.17	.94	.65	363.71
38	2500	—	—	—	SOIC	HCPL062N-ND	5.22	4.35	3.13	—
	3750	50	13	7.0	SOICW	HCPL0637-ND	2.41	2.13	1.38	—
	3750	—	—	—	SOICW	HCPL0638-ND	2.56	2.27	1.47	—
39	2500	—	—	—	SMD	HCPL2631SDCT-ND‡	2.43	2.18	1.41	880.46
40	5300	1.6	5	16	DIP	H11L1-MQT-ND	.88	.69	.50	—
	5300	1.6	5	16	SMD	H11L1SM-ND	.95	.74	.53	—
	7500	60	5	15	SMD	H11L1SR2MCT-ND‡	1.01	.78	.56	301.87
	7500	1.6	5	15	SMD	H11L1SR2VMCT-ND‡	.99	.79	.55	307.36
	7500	1.6	5	15	SMD	H11L1SVM-ND†	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TM-ND	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TVM-ND†	.95	.74	.53	—
	5300	1.6	5	16	DIP	H11L1V-MQT-ND†	.88	.69	.49	—
	7500	1.6	5	15	DIP	H11L1VM-ND	.95	.74	.53	—
	5300	10	5	16	DIP	H11L2-MQT-ND	.58	.49	.39	—
	7500	10.0	5	15	SOIC	H11L2M-ND	.95	.74	.53	—
	7500	10.0	5	15	SMD	H11L2SM-ND	.91	.74	.52	—
	7500	10.0	5	15	SMD	H11L2SR2MCT-ND‡	.99	.79	.55	307.36
	7500	10.0	5	15	SMD	H11L2SVM-ND†	.91	.74	.52	—
	7500	10.0	5	15	DIP	H11L2TVM-ND†	.91	.74	.52	—
	7500	10.0	5	15	DIP	H11L2VM-ND†	.95	.74	.53	—
	7500	60	5	16	DIP	H11L3M-ND	.95	.74	.53	—
	5300	3.2	10	16	DIP	H11N1-MQT-ND	2.41	2.13	1.38	—
5300	10	10	16	DIP	H11N3-M-ND	2.37	2.10	1.36	—	

Fig.	Tension d'isolement	Délais de propagation max. (ns)	CMR typique V/µs	I _F (mA)	Type boîtier	N° de référence Digi-Key	Prix unitaire		
							1	10	100
29	2500	100	10,000	50	SMD	6N137S-ND	.95	.77	.54
	2500	100	10,000	50	SMD	HCPL0601R1CT-ND‡	3.03	2.72	1.76
	2500	100	10,000	50	SMD	HCPL0601R1TR-ND◊	1098.25/1000		
41	2500	75	10,000	5	DIP	6N137OT-ND	.95	.77	.54
	2500	75	10,000	5	DIP	HCPL2601QT-ND	1.55	1.38	.89
	2500	75	10,000	5	DIP	HCPL2611-ND	1.77	1.57	1.02
42	2500	75	10,000	5	DIP	HCPL2630QT-ND	2.88	2.56	1.65
	2500	75	10,000	5	DIP	HCPL2631QT-ND	2.24	1.99	1.29